



RE016-LF

- DIL-Labcard
- Epoxy fibre-glass 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-Leadfree)
- 25 x 25 soldering pads 2.00 x 2.00 mm
- Hole spacing 2.54 x 2.54 mm
- Hole diameter 1.00 mm
- Size 67.94 x 68.58 mm